



511.40998X00

3724

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): N. KOYAMA et al
Serial No.: 10/018,188
Filed: December 18, 2001
For: CMP ABRASIVE, METHOD FOR POLISHING SUBSTRATE
AND METHOD FOR MANUFACTURING SEMICONDUCTOR
DEVICE USING THE SAME, AND ADDITIVE FOR CMP
ABRASIVE
Group: 3724
Examiner: T. ELEY

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AMENDMENT

MS: AMENDMENTS

Commissioner For Patents
POB 1450
Alexandria, VA 22313-1450

August 25, 2004

Sir:

In response to the Office Action dated February 25, 2004, the period of response for which extension of time is requested in the attached Petition for Extension of Time, please amend the above-identified application as listed below and as set forth on the following pages:

Amendments to the Specification;

Amendments to the Claims; and

Remarks are included following the Amendments.